12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130307000
WCSP Qualification of JCAP as an additional front end (bump) and backend (assembly) for BQ27520YZF Device
Change Notification / Sample Request

Date: 3/14/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130307000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ27520YZFT-G1	null
BQ27520YZFT-G3	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130307000	**PCN Date:**	03/14/2013

Title:	WCSP Qualification of JCAP as an additional front end (bump) and backend (assembly) for BQ27520YZF Device

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	06/14/2013	**Estimated Sample Availability:**	Date provided at sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☒	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

WCSP Qualification of JCAP as an additional front end (bump) and backend (assembly) for BQ27520YZF device. Current front end (bump) and backend (assembly) is at TI Clark.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

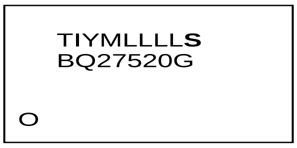
Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Assembly Site

TI Clark	Assembly Site Origin (22L)	ASO: QAB
JCAP	Assembly Site Origin (22L)	ASO: JCP


TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
Pb
G4
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO:SHE (21L) CCO:USA
(22L) ASO:MLA (23L) ACO:MYS



TI = TI LETTERS
YM = YEAR MONTH DATE CODE
LLLL = ASSEMBLY LOT CODE
S = ASSEMBLY SITE CODE
O = Pin A1

Assembly Site Code for TI Clark = I
Assembly Site Code for JCAP = P

Product Affected:

BQ27520YZFR-G1	BQ27520YZFR-G4	BQ27520YZFT-G3	HPA02235YZFR
BQ27520YZFR-G3	BQ27520YZFT-G1	BQ27520YZFT-G4	HPA02254YZFR

Qualification Data: Approved 05/10/2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device : BQ27520YZF (MSL1-260C)

Package / Die Construction Details

Assembly(backend) Site:	JCAP	Bump(front end) site	JCAP
Pin Count, Package Family:	15-YZF, DSBGA	Bump Process:	RDL
Bump Composition:	SnAgCu	Bump Diam:	11.81 mils

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	Pass	-	-
High Temp Operating Life	150C (300 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (700 Cyc)	77/0	77/0	77/0
Physical Dimensions	(per mechanical drawing)	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes: ** Preconditioning sequence Level 1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com